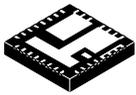


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

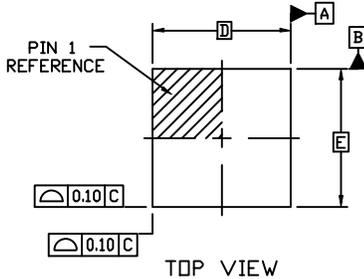
ON Semiconductor®



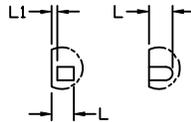
QFN31 5x5, 0.5P CASE 485FG ISSUE A

DATE 27 JUL 2017

SCALE 2:1



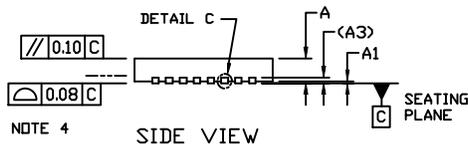
TOP VIEW



DETAIL A
ALTERNATE TERMINAL
CONSTRUCTIONS

NOTES:

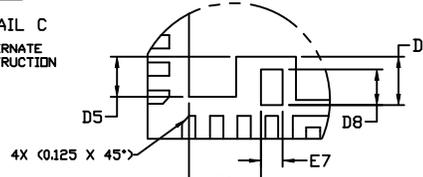
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* APPLIES TO THE PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



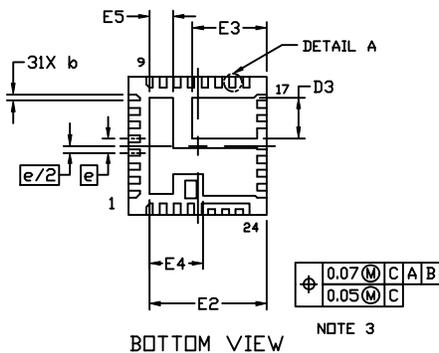
SIDE VIEW



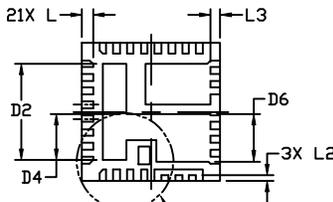
DETAIL C
ALTERNATE
CONSTRUCTION



DETAIL B 2:1

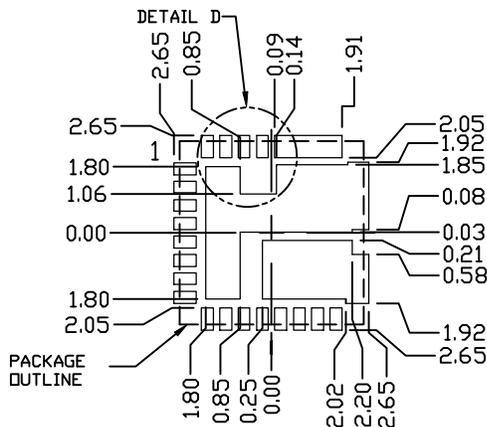


BOTTOM VIEW

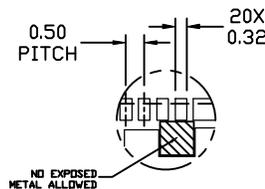


SUPPLEMENTAL
BOTTOM VIEW

DIM	MILLIMETERS	
	MIN.	MAX.
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
<i>b</i>	0.18	0.30
D	5.00	BSC
D2	3.45	3.55
D3	1.43	1.53
D4	1.63	1.83
D5	0.69	0.79
D6	1.68	1.78
D7	0.89	REF
D8	0.65	REF
E	5.00	BSC
E2	4.15	4.35
E3	2.60	2.80
E4	1.89	1.99
E5	0.80	0.90
E6	1.30	REF
E7	0.40	REF
<i>e</i>	0.50	BSC
L	0.30	0.50
L1	---	0.15
L2	0.20	REF
L3	0.35	REF

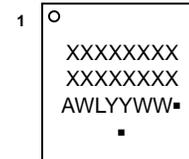


RECOMMENDED
MOUNTING FOOTPRINT



DETAIL D

GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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NEW STANDARD:		
DESCRIPTION:	QFN31 5x5, 0.5P	PAGE 1 OF 2

